Amendments to the Specification:

Please replace the paragraph beginning on page 4, line 20, with the following rewritten paragraph:

In the vitrified bond tool according to the first aspect of the invention, the abrasive grains bonded to the vitrified bond tool are positioned relative to each other so as to be spaced apart from each other, so that each of the abrasive grains is bonded at a ~~sufficiently~~ large area of a surface thereof to the vitrified bond layer. Thus, all of the abrasive grains are bonded to the vitrified bond layer with sufficiently large bonding strength, thereby preventing removal of the abrasive grains from the vitrified bond layer or the support body, when this vitrified bond tool is used as a polishing or grinding tool for polishing or grinding a workpiece, or as a dressing tool for dressing a polishing or grinding tool. The workpiece polished or ground by this vitrified bond tool, or the polishing or grinding tool dressed by this vitrified bond tool and a workpiece polished or ground by the polishing or grinding tool is advantageously prevented from being contaminated and damaged by removal of the abrasive grains. The vitrified bond tool maintains its cutting sharpness throughout successive polishing or grinding operations, and accordingly exhibits an excellent polishing or grinding performance with high stability. In view of these advantages, the vitrified bond tool of this invention is suitable for dressing a polishing pad which is required to assure a high degree of flatness in a surface of a semiconductor wafer by polishing a considerably small amount of the surface of the wafer.

Please replace the paragraph beginning on page 6, line 6, with the following rewritten paragraph:

In the present vitrified bond tool in which each of the abrasive grains is bonded at a ~~sufficiently~~ large area of its surface to the vitrified bond layer, all of the abrasive grains are bonded to the vitrified bond layer with sufficiently large bonding strength, even with a reduced thickness of the vitrified bond layer. The reduced thickness of the vitrified bond

layer facilitates protrusions of the abrasive grains from the vitrified bond layer after a firing step, i.e., after the manufacture of the tool, so that the vitrified bond tool does not have to be subjected to a truing operation, prior to an initial use thereof. That is, the vitrified bond tool exhibits an expected polishing or grinding performance even in the initial use without the truing operation.

Please replace the paragraph beginning on page 15, line 25, with the following rewritten paragraph:

In the vitrified bond tool manufactured according to the present method, the first abrasive grains are held by the vitrified bond layer so as to be fixed relative to the dressing surface and are spaced apart from each other, while the second abrasive grains are held by the vitrified bond layer so as to be fixed relative to the dressing surface and are mingled together with each other such that the second abrasive grains are positioned between the first abrasive grains and are spaced apart from the first abrasive grains. Since at least the surface layer which is partially constituted by the dressing surface is made of the inorganic material, there is no risk of effluence of a metallic component even if a strong-acid fluid is used as the polishing fluid. Since the second abrasive grains whose average diameter is smaller than the average diameter of the first abrasive grains are positioned to be spaced apart from each other or to be spaced apart from the first abrasive grains, each of the second abrasive grains is bonded at a ~~sufficiently~~ large area of a surface thereof to the vitrified bond layer with a sufficiently large bonding strength. Further, the presence of the second abrasive grains between the first abrasive grains on the vitrified bond layer prevent the vitrified bond layer from being brought in contact with the polishing pad, thereby avoiding breakage of the vitrified bond layer.

Please replace the paragraph beginning on page 64, line 2, with the following rewritten paragraph:

As described above, in the dressing tool 124 of the present invention, the first and second abrasive grains 136, 138 are held by the vitrified bond layer 140 to be fixed to the dressing surface 130, such that the first abrasive grains 136 are positioned to be spaced apart from each other, while the second abrasive grains 138 whose average diameter is smaller than that of the first abrasive grains 136 are mingled together with each other and are positioned to be spaced apart from the first abrasive grains 136. Since at least the surface layer which is partially constituted by the dressing surface 130 is made of the inorganic material, there is no risk of effluence of a metallic component even if a strong-acid fluid is used as the polishing fluid. Since the second abrasive grains 138 are positioned to be spaced apart from each other or to be spaced apart from the first abrasive grains 136, each of the second abrasive grains 138 is bonded at a ~~sufficiently~~ large area of a surface thereof to the vitrified bond layer 140 with a sufficiently large bonding strength. Further, the presence of the second abrasive grains 138 between the first abrasive grains 136 on the vitrified bond layer 140 prevent the vitrified bond layer 140 from being brought in contact with the polishing pad 118, thereby avoiding breakage of the vitrified bond layer 140.

Please replace the paragraph beginning on page 65, line 23, with the following rewritten paragraph:

In the dressing tool 124 produced as described above, the first and second abrasive grains 136, 138 are held by the vitrified bond layer 140 to be fixed to the dressing surface 130, such that the first abrasive grains 136 are positioned to be spaced apart from each other, while the second abrasive grains 138 whose average diameter is smaller than that of the first abrasive grains 136 are mingled together with each other and are positioned to be spaced apart from the first abrasive grains 136. Since at least the surface layer which is partially

constituted by the dressing surface 130 is made of the inorganic material, there is no risk of effluence of a metallic component even if a strong-acid fluid is used as the polishing fluid. Since the second abrasive grains 138 are positioned to be spaced apart from each other or to be spaced apart from the first abrasive grains 136, each of the second abrasive grains 138 is bonded at a ~~sufficiently~~ large area of a surface thereof to the vitrified bond layer 140 with a sufficiently large bonding strength. Further, the presence of the second abrasive grains 138 between the first abrasive grains 136 on the vitrified bond layer 140 prevent the vitrified bond layer 140 from being brought in contact with the polishing pad 118, thereby avoiding breakage of the vitrified bond layer 140.